

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"20020171153"	USPAT	OR	OFF	2005/01/28 16:23
L2	1	"20020171153"	US-PGPUB; USPAT	OR	OFF	2005/01/28 16:24
L3	1	"20030122259"	US-PGPUB; USPAT	OR	OFF	2005/01/28 16:24
L4	2613	257/698	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 16:37
L5	3668	257/774	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 16:46
L6	3729	257/773	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 17:06
L7	4416	257/778	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 17:48
L8	2790	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 18:06
L9	1133	257/781	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 18:54
L10	2183	257/780	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:09

L11	2824	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:28
L12	16	"6482730".pn. or "6344696".pn. or "6245598".pn. or "6177725". pn. or "6153448".pn. or "6028354".pn. or "5990545".pn. or "5866949".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:32
L13	382070	(semiconductor or die or chip or IC) and (step or groove or recess or open\$3) with (board or PCT or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:35
L14	382018	(semiconductor or die or chip or IC) and (step or groove or recess or open\$3) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:39
L15	50028	14 and (encapsulat\$3 or module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:36
L16	129330	14 and (encapsulat\$3 or mod\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:38
L17	55365	16 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:38
L18	38727	14 and (encapsulat\$3 or mod\$3) with (step or groove or recess or open\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:39

L19	17822	18 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:40
L20	179232	(semiconductor or die or chip or IC) and (step or groove) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/28 19:39
L21	22292	20 and (encapsulat\$3 or mod\$3) with (step or groove)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:39
L22	10051	21 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:40
L23	2130	22 and (step or groove) with (edge or peripher\$3 or perimeter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:42
L24	995	22 and (step or groove) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:45
L25	26364	(semiconductor or die or chip or IC) and (step or groove) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:39
L26	5366	25 and (encapsulat\$3 or mold\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:48

L27	2641	26 and wir\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 19:48
L28	1423	26 and wir\$3	USPAT	OR	ON	2005/01/28 19:53
L29	1109	28 not 24	USPAT	OR	ON	2005/01/28 19:53
L30	2	"0050419".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:09
L31	1	"5345106".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:09
L32	1	"5661092".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
L33	1	"5808359".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
L34	1	"6166446".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
L35	1	"6249433".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:10
L36	1	"6323549".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
L37	1	"6436550".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
L38	1	"6552417".PN.	USPAT; USOCR	OR	OFF	2005/01/28 20:11
L39	15012	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or substrate or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:41
L40	7660	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or module or carrier or mount\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:42
L41	3226	(semiconductor or die or chip or IC) and (step\$3 or ledge) with (edge or peripher\$3 or perimeter) with (board or PCB or module or carrier or mount\$3)	USPAT	OR	ON	2005/01/28 20:43
L42	2703	41 not 28	USPAT	OR	ON	2005/01/28 20:43
L43	98	41 not 28 and (wire) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:47
L44	58	41 not 28 and (wiring) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:47

L45	58	42 and (wiring) and (encapsulat\$3 or mold\$3)	USPAT	OR	ON	2005/01/28 20:49
L46	2	40 and (wiring) and (encapsulat\$3 or mold\$3)	JPO	OR	ON	2005/01/28 20:58
L47	2	"5964174"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 20:58
L48	14	"5864174"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:14
L49	1	"4695870".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
L50	1	"4855869".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
L51	1	"5030796".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:00
L52	1	"5175610".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:01
L53	1	"5216278".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:01
L54	1	"5264726".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:05
L55	1	"5291374".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:05
L56	1	"5311057".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
L57	1	"5319241".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
L58	1	"5436203".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
L59	1	"5450283".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
L60	1	"5455456".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:06
L61	1	"5467253".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
L62	1	"5477611".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
L63	1	"5496775".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07

L64	1	"5508556".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
L65	1	"5528083".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:07
L66	1	"5621242".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
L67	1	"5621242".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
L68	1	"5633785".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
L69	1	"5686362".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
L70	1	"5789809".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
L71	1	"5866949".PN.	USPAT; USOCR	OR	OFF	2005/01/28 21:08
L72	3835	257/678	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:34
L73	2	"5216278".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 21:34
S1	3408	257/774	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 18:46
S2	4073	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 18:58
S3	2615	257/786	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/02 19:06
S5	1	"20020171153"	US-PGPUB; USPAT	OR	OFF	2004/09/02 11:21
S6	1	"20020171153" and board with (insulat\$3 or dielectric)	US-PGPUB; USPAT	OR	ON	2004/09/02 11:57
S7	1	"5736791".pn.	US-PGPUB; USPAT	OR	ON	2004/09/02 18:28